## Thermally Stable Solder Paste WS (Water-Soluble) Sn96.5/Ag3.0/Cu0.5 T4 (500g jar)

## Product Highlights

Revolutionary Formula: No Refrigeration Required!
Printing speeds up to $100 \mathrm{~mm} / \mathrm{sec}$
Long stencil life
Wide process window
Excellent Wetting with Moderate Activity (REMO) Flux
Water-Soluble Easily cleaned with water $\left(60^{\circ} \mathrm{C}+\right)$

Low voiding<br>Compatible with most board finishes<br>Print grade<br>Compatible with enclosed print heads<br>RoHS 3 and REACH compliant

## Specifications

Alloy:
Mesh Size:
Micron ( $\mu \mathrm{m}$ ) Range:
Flux Type:
Flux Classification:
Metal Load:
Melting Point:
Packaging:
Shelf Life:

Sn96.5/Ag3.0/Cu0.5
T4
20-38
Synthetic Water-Soluble
REM0 (Residue must be water-washed at $60^{\circ} \mathrm{C}+$ after reflow)
88.75\% Metal by Weight
$217^{\circ} \mathrm{C}\left(423^{\circ} \mathrm{F}\right)$
500 g Jar
Refrigerated >6 months, Unrefrigerated >6 months *See notes below:

*Shelf Life Notes: Chip Quik® solder paste is good past its quoted shelf life, regardless of refrigeration. Before use, visually inspect the solder paste to ensure it is not dried out or clumpy, or check stencil release. If stored in a jar, stir the product thoroughly for 2-3 minutes before inspection and use.

Chip Quik® solder paste is manufactured using Made in USA high quality synthetic flux and precision atomized metal powder. Chip Quik® solder paste is guaranteed for 12 months from date of manufacture, regardless of refrigeration. If you have any issues with our solder paste, please contact Chip Quik® directly for no charge warranty replacement. Please retain original bill of sale, and solder paste in original container as we may request its return for internal R\&D testing purposes.

## Printer Operation

Print Speed: 25-100mm/sec
Squeegee Pressure: $70-250 \mathrm{~g} / \mathrm{cm}$ of blade
Under Stencil Wipe: Once every 10-25 prints, or as necessary

## Stencil Life

$>8$ hours @ 20-50\% RH $22-28^{\circ} \mathrm{C}\left(72-82^{\circ} \mathrm{F}\right)$
$>4$ hours @ 50-70\% RH 22-28으 (72-82ํ. $)$

## Stencil Cleaning

Automated stencil cleaning systems for both stencil and misprinted boards. Manual cleaning using isopropyl alcohol (IPA).

## Storage and Handling

Store at $3-25^{\circ} \mathrm{C}\left(37-77^{\circ} \mathrm{F}\right)$. Do not freeze. Refrigeration is not required, but will extend shelf life. Allow 4 hours for solder paste to reach an operating temperature of $20-25^{\circ} \mathrm{C}\left(68-77^{\circ} \mathrm{F}\right)$ before use.

## Transportation

This product has no shipping restrictions. Shipping below $0^{\circ} \mathrm{C}\left(32^{\circ} \mathrm{F}\right)$ or above $25^{\circ} \mathrm{C}\left(77^{\circ} \mathrm{F}\right)$ for normal transit times by ground or air will not impact this product's stated shelf life.

## Recommended Profile

Reflow profile for $\operatorname{Sn} 96.5 / \mathrm{Ag} 3.0 / \mathrm{Cu} 0.5$ solder assembly, designed as a starting point for process optimization.


Test Results

| Test J-STD-004 or other requirements as stated | Test Requirement | Result |
| :---: | :---: | :---: |
| Copper Mirror | IPC-TM-650: 2.3.32 | L: No breakthrough |
| Corrosion | IPC-TM-650: 2.6.15 | L: No corrosion |
| Quantitative Halides | IPC-TM-650: 2.3.28.1 | L: <0.05\% |
| Electrochemical Migration | IPC-TM-650: 2.6.14.1 | $\mathrm{L}:<1$ decade drop |
| Surface Insulation Resistance $85^{\circ} \mathrm{C}$, 85\% RH @ 168 Hours | IPC-TM-650: 2.6.3.7 | $\mathrm{L}: \geq 100 \mathrm{M} \Omega$ |
| Tack Value | IPC-TM-650: 2.4.44 | 37 g |
| $\begin{aligned} & \text { Viscosity - Malcom @ } 10 \text { RPM } / 25^{\circ} \mathrm{C} \\ & \left(\times 10^{3} \mathrm{mPa} / \mathrm{s}\right) \end{aligned}$ | IPC-TM-650: 2.4.34.4 | Print: 155-215, Dispense: 80-115 |
| Visual | IPC-TM-650: 3.4.2.5 | Clear and free from precipitation |
| Conflict Minerals Compliance | Electronic Industry Citizenship Coalition (EICC) | Compliant |
| REACH Compliance | Articles 33 and 67 of Regulation (EC) <br> No 1907/2006 | Contains no substance $>0.1 \% \mathrm{w} / \mathrm{w}$ that is listed as a SVHC or restricted for use in solder materials |

Conforms to the following Industry Standards:
J-STD-004B, Amendment 1 (Solder Fluxes): Yes
J-STD-005A (Solder Pastes): Yes
J-STD-006C, Amendments 1 \& 2 (Solder Alloys and Fluxed/Non-Fluxed Solders): Yes
RoHS 3 Directive (EU) 2015/863: Yes

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